

Part Number: ZDG54W-1

2.0x1.25mm SMD CHIP LED LAMP

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Package : 2000 pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant





Package Schematics POLARITY MARK 0.13[0.005] .25[0.049] 1 -2 \square - 2 1 2[0.079] 1.3[0.051] 1.2[0.047] 0.25[0.01] 0.75[0.03] 0.4[0.016] 0.4[0.016] (1)(2)

1. All dimensions are in millimeters (inches).

Notes:

2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		DG (InGaN)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	PD	102.5	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Electrostatic Discharge Threshold (HBM)	450	V		

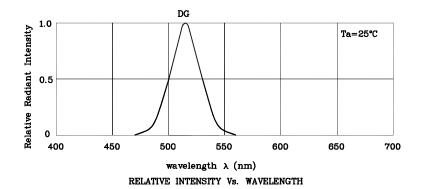
DISCHARGE SENSITIVE DEVICES

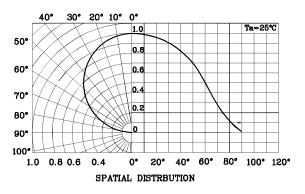
Operating Characteristics (T _A =25°C)		DG (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	4.1	V
Reverse Current (Max.) (V _R =5V)	I_R	50	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λP	515	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λD	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
ZDG54W-1	Green	InGaN	Water Clear	280	447	515	120°
Apr 11,2011					SDSA73	19 V3 Layout:	Maggie L.

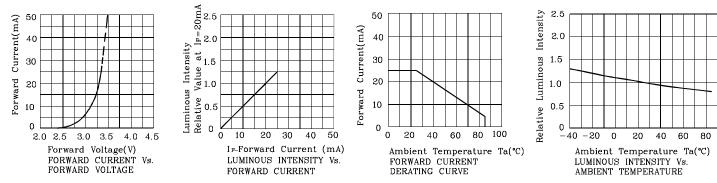
This datasheet has been downloaded from http://www.digchip.com at this page



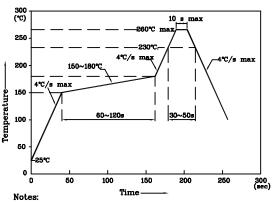








LED is recommended for reflow soldering and soldering profile is shown below.



Reflow Soldering Profile for SMD Products (Pb-Free Components)

1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

high temperatures conditions

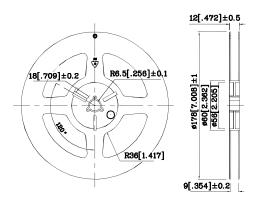


The device has a single mounting surface. The device must be mounted according to the specifications.

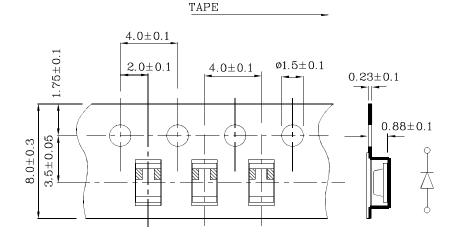
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS

